

HVL400C

Variable Capacitance Diode for VCO

REJ03G0226-0100Z Rev.1.00 Apr 22, 2004

Features

- High capacitance ratio. (n = 1.60 min)
- Low series resistance. (rs = 0.70Ω max)
- Extremely small Flat Package (EFP) is suitable for surface mount design.

Ordering Information

Type No.	Laser Mark	Package Code
HVL400C	Х	EFP

Pin Arrangement

Cathode mark	
	1. Cathode 2. Anode



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

ltem	Symbol	Value	Unit
Reverse voltage	V _R	15	V
Junction temperature	Tj	125	°C
Storage temperature	Tstg	–55 to +125	°C

Electrical Characteristics

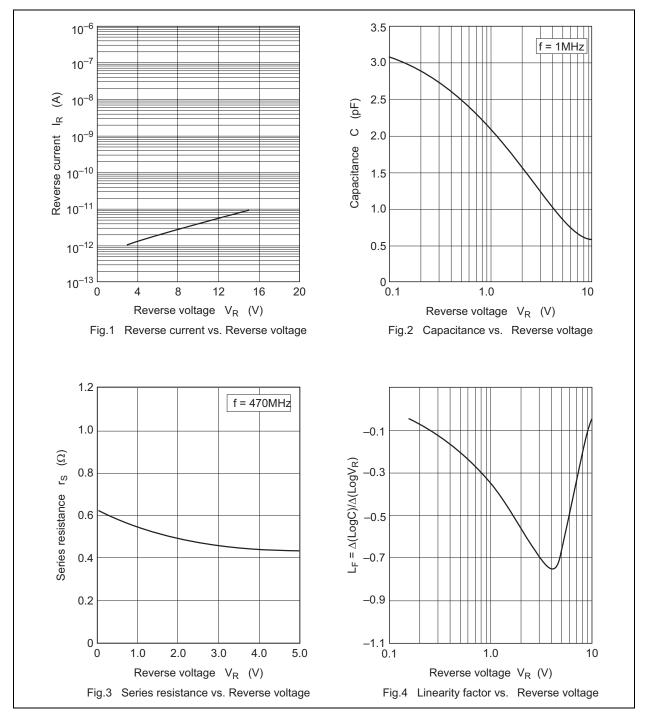
 $(Ta = 25^{\circ}C)$ Item Symbol Min Тур Max Unit **Test Condition** $V_{R} = 15 V$ Reverse current 10 I_{R1} nA — 50 V_R = 15 V, Ta = 60°C I_{R2} — — Capacitance C_1 2.24 $V_R = 1 V, f = 1 MHz$ 2.05 pF 1.18 1.29 $V_R = 3 V, f = 1 MHz$ C_3 _ Capacitance ratio n 1.60 ___ 1.85 _ C₁ / C₃ Series resistance _ 0.70 $V_R = 1 V, f = 470 MHz$ ____ Ω rs

Notes: 1. Please do not use the soldering iron due to avoid high stress to the EFP package.

2. The material of lead is exposed for cutting plane. There for, soldering nature of lead tip part is considered as unquestioned. Please kindly consider soldering nature.

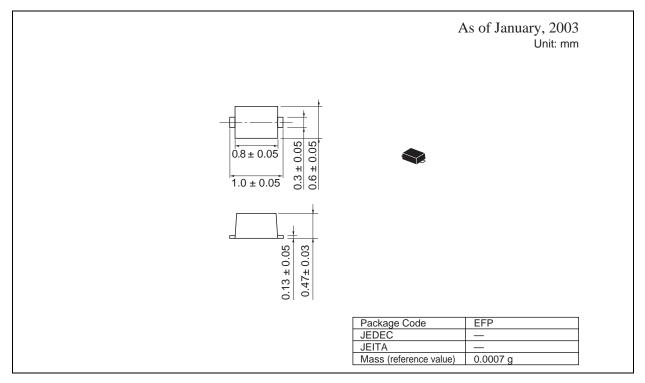


Main Characteristic





Package Dimensions





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Renesas Technology America, Inc. 450 Holger Way, San Jose, CA 95134-1368, U.S.A Tel: <1> (408) 382-7500 Fax: <1> (408) 382-7501

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Renesas Technology Europe GmbH Dornacher Str. 3, D-85622 Feldkirchen, Germany Tel: <49> (89) 380 70 0, Fax: <49> (89) 929 30 11

Renesas Technology Hong Kong Ltd. 7/F., North Tower, World Finance Centre, Harbour City, Canton Road, Hong Kong Tel: <852> 2265-6688, Fax: <852> 2375-6836

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Renesas Technology (Shanghai) Co., Ltd. 26/F., Ruijin Building, No.205 Maoming Road (S), Shanghai 200020, China Tel: <86> (21) 6472-1001, Fax: <86> (21) 6415-2952

Renesas Technology Singapore Pte. Ltd. 1, Harbour Front Avenue, #06-10, Keppel Bay Tower, Singapore 098632 Tel: <65> 6213-0200, Fax: <65> 6278-8001